

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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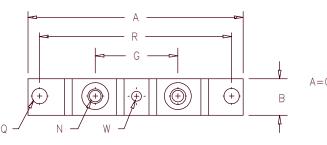
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





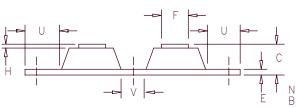


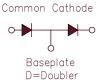
Schottky PowerMod











Baseplate: Nickel plated copper

| Dim. Inches | | Millimeters | | |
|---|----------------------------------|--|-------------------------------------|----------------|
| Min. | Max. | Min. | Max. | Notes |
| B 0.700 C E 0.120 F 0.490 G 1.375 H 0.010 N Q 0.275 R 3.150 U 0.600 V 0.312 | 0.510 BSC 0.290 BSC | 34.92 0.25 6.99 80.0 15.24 7.92 | 12.95 2 BSC 7.37 1 BSC | 1/4-28 Dia. |

| Microsemi Catalog Number | Industry Part Number | Working Peak Reverse Voltage | |
|-----------------------------|--|---------------------------------|------------|
| CPT20130* CPT20135* | MBR20030CT 200CNQ035 224CNQ035 MBR20035CT | 30V 35V | 30V 35V |
| CPT20140* | 200CNQ040 224CNQ040 MBR20040CT | 40V | 40V |
| CPT20145* | 200CNQ045 224CNQ045 MBR20045CT | 45V | 45V |
| *Add Suf | fix A for Com | mon Anode D fo | r Doubler |

*Add Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- 200 Amperes/30 to 45 Volts
- 150° C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

|F(AV) 200 Amps Average forward current per pkg Average forward current per leg F(AV) 100 Amps İFSM Maximum surge current per leg 2000 Amps Maximum repetitive reverse current per leg | R(OV) 2 Amps VFM 0.68 Volts Max peak forward voltage per leg V_{FM} Max peak forward voltage per leg 0.64 Volts ^IRM 1100mA Max peak reverse current per leg Max peak reverse current per leg ^IRM 4.0mA C_J $VR = 5.0V, TC = 25^{\circ}C$ 5500pF Typical junction capacitance

 ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .20°C/W ^{T}C = 99°C, Square wave, $^{R}\Theta JC$ = .40°C/W 8.3ms, half sine, TJ = 125°C f = 1 KHZ, 25°C FM = 200A: TJ = 25°C* FM = 200A: TJ = 125°C* VRRM, TJ = 125°C* VRRM, TJ = 25°C*

*Pulse test: Pulse width 300 usec, Duty cycle 2%

Thermal and Mechanical Characteristics

TSTG Storage temp range -55°C to 150°C ΤJ -55°C to 150°C 0.40°C/W Junction to case Operating junction temp range R OJC Max thermal resistance per leg Recs Typical thermal resistance (greased) 0.08°C/W Case to sink Terminal Torque 35-40 inch pounds Mounting Base Torque (outside holes) Mounting Base Torque (center hole) 30-40 inch pounds 8-10 inch pounds center hole must be torqued first Weight 2.8 ounces (75 grams) typical



CPT20130 - CPT20145

Figure 1 Maximum Forward Characteristics — Per Leg

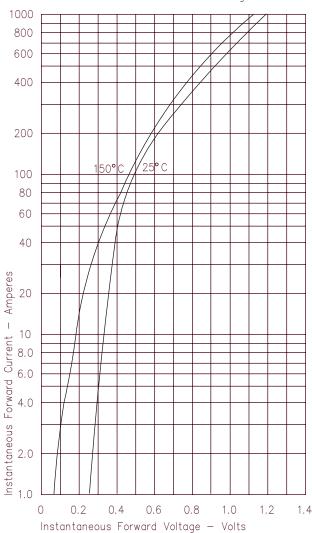


Figure 3
Typical Junction Capacitance — Per Leg

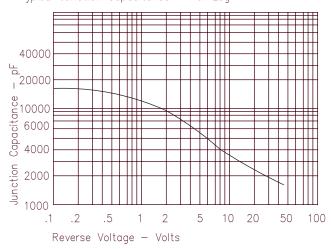


Figure 4 Forward Current Derating — Per Leg

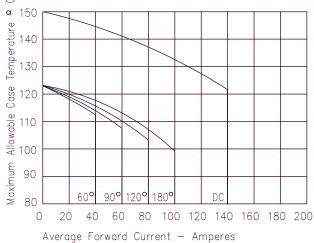


Figure 2 Typical Reverse Characteristics — Per Leg

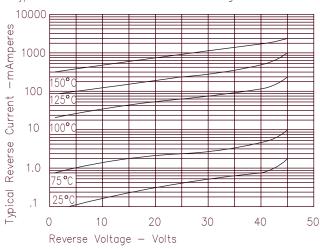
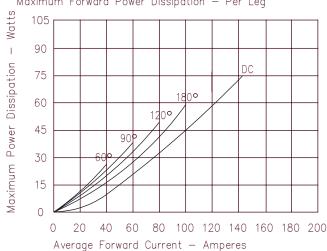


Figure 5
Maximum Forward Power Dissipation — Per Leg





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